

Please amend the claims as follows. This listing of claims will replace all prior versions, and listings of claims in the application:

**Listing of Claims:**

Claim 1 (Previously Presented): An apparatus for chemical mechanical polishing a surface of a workpiece, comprising:

a housing configured to encase a processing area, the processing area including,  
a wafer loading and unloading station;  
a plurality of polishing areas; and  
a handler configured to include a leaf structure rotatably coupled to a turret,  
the leaf structure including a pair of carrier devices designed to hold a pair of  
workpieces to be polished on one of the polishing areas,  
wherein the pair of workpieces are capable of being polished substantially at the same  
time on one of the plurality of the polishing areas.

Claim 2 (Previously Presented): An apparatus for chemical mechanical polishing a surface of a workpiece as recited in claim 1, wherein the leaf structure is configured to rotate about the turret so as to move the pair of workpieces between the loading and unloading area and the polishing area.

Claim 3 (Original): An apparatus for chemical mechanical polishing a surface of a workpiece as recited in claim 1, wherein each polishing area includes a polishing pad overlying a rotating platen assembly.

Claim 4 (Original): An apparatus for chemical mechanical polishing a surface of a workpiece as recited in claim 1, wherein each carrier device is configured to include an actuator designed to adjust the carrier device in a z-direction.

Claim 5 (Original): An apparatus for chemical mechanical polishing a surface of a workpiece as recited in claim 1, wherein the leaf structure rotates horizontally about the turret along a fixed plane.

Claim 6 (Original): An apparatus for chemical mechanical polishing a surface of a workpiece as recited in claim 1, wherein the leaf structure includes a pair of fingers, each finger designed to support the respective carrier device.

Claim 7 (Original): An apparatus for chemical mechanical polishing a surface of a workpiece as recited in claim 6, wherein each finger includes a stop.

Claim 8 (Original): An apparatus for chemical mechanical polishing a surface of a workpiece as recited in claim 1, wherein each carrier device includes an upper stop assembly configured to absorb a sudden movement of the carrier device in a z-direction.

Claim 9 (Currently Amended): A chemical mechanical polishing apparatus, comprising:

a polishing area; and

a leaf structure rotatably coupled to a turret, the leaf structure having a pair of fingers, each finger configured to include a carrier device designed to hold a workpiece to be polished, carrier devices configured to apply the workpieces together onto the polishing area.

Claim 10 (Original): A chemical mechanical polishing apparatus of claim 9, wherein each carrier device rotates about the turret along a common axis.

Claim 11 (Original): A chemical mechanical polishing apparatus of claim 9, wherein each carrier device includes an actuator to adjust the carrier device in a direction perpendicular to the polishing area.

Claim 12 (Original): A chemical mechanical polishing apparatus of claim 9, wherein the leaf structure is configured to rotate about the turret independently so as to move the workpiece between a loading and unloading area and the polishing area.

Claim 13 (Original): A chemical mechanical polishing apparatus of claim 9, wherein the polishing area includes a polishing pad overlying a rotating platen.

Claim 14 (Original): A chemical mechanical polishing apparatus of claim 9, wherein the carrier device is configured to include an actuator designed to adjust the carrier device in a z-direction.

Claim 15 (Original): A chemical mechanical polishing apparatus of claim 9, wherein each finger includes a stop, the stop being configured to prevent the leaf structure from colliding as the leaf structure rotates about the turret.

Claim 16 (Original): A chemical mechanical polishing apparatus of claim 9, wherein each carrier device includes an upper stop assembly configured to absorb a sudden movement of the carrier device in a z-direction.

Claim 17 (Cancelled)

Claim 18 (Currently Amended): A chemical mechanical polishing apparatus, comprising:

a plurality of polishing areas; and

a pair of leaf structures rotatably coupled to a turret, each leaf structure configured to include a pair of fingers, each pair of fingers configured to hold a pair of carrier devices each designed to hold a workpiece to be polished,

wherein each pair of carrier devices is configured to be applied together onto a respective polishing area.

Claim 19 (Original): A chemical mechanical polishing apparatus of claim 18, wherein each pair of carrier devices are applied onto the respective polishing area substantially at the same time.

Claim 20 (Previously Presented): A chemical mechanical polishing apparatus of claim 18, wherein the pair of leaf structures is configured to rotate about the turret in an independent manner.

Claim 21 (Original): A chemical mechanical polishing apparatus of claim 18, wherein each leaf structure is configured to move an associated workpiece between a loading and unloading area and the respective polishing area.

Claim 22 (Original): A chemical mechanical polishing apparatus of claim 18, wherein each finger includes a stop, the stop being configured to prevent the pair of leaf structures from colliding as the leaf structures rotate about the turret.

Claim 23 (Previously Presented): An apparatus for chemical mechanical polishing a surface of a workpiece, comprising:

a housing configured to encase a processing area, the processing area including,

a wafer loading and unloading station;

a plurality of polishing areas; and

a handler configured to include a leaf structure rotatably coupled to a turret,

the leaf structure including a pair of carrier devices designed to hold a pair of workpieces to be polished on at least one of the polishing areas, each leaf structure including a pair of fingers, each finger designed to support the respective carrier device, each finger further including a stop,

wherein the pair of workpieces are capable of being polished substantially at the same time on the at least one of the plurality of the polishing areas.

Claim 24 (Previously Presented): An apparatus for chemical mechanical polishing a surface of a workpiece, comprising:

a housing configured to encase a processing area, the processing area including,

a wafer loading and unloading station;

a plurality of polishing areas; and

a handler configured to include a leaf structure rotatably coupled to a turret, the leaf structure including a pair of carrier devices designed to hold a pair of workpieces to be polished on at least one of the polishing areas, each carrier device including an upper stop assembly configured to absorb a sudden movement of the carrier device in a z-direction,

wherein the pair of workpieces are capable of being polished substantially at the same time on the at least one of the plurality of the polishing areas.

Claim 25 (Currently Amended): A chemical mechanical polishing apparatus, comprising:

a polishing area; and

a leaf structure rotatably coupled to a turret, the leaf structure having a pair of fingers, each finger configured to include a carrier device designed to hold a workpiece to be polished, each carrier device configured to apply each of the workpieces onto the polishing area, each finger including a stop, the stop being configured to prevent the leaf structure from colliding as the leaf structure rotates about the turret.

Claim 26 (Currently Amended): A chemical mechanical polishing apparatus, comprising:

a polishing area; and

a leaf structure rotatably coupled to a turret, the leaf structure having a pair of fingers, each finger configured to include a carrier device designed to hold a workpiece to be polished, each carrier device configured to apply each of the workpieces onto the polishing

area, each carrier device including an upper stop assembly configured to absorb a sudden movement of the carrier device in a z-direction.

Claim 27 (Currently Amended): A chemical mechanical polishing apparatus, comprising:

a plurality of polishing areas; and

a pair of leaf structures rotatably coupled to a turret, each leaf structure configured to include a pair of fingers, each pair of fingers configured to hold a pair of carrier devices each designed to hold a workpiece to be polished, each finger including a stop, the stop being configured to prevent the pair of leaf structures from colliding as the leaf structures rotate about the turret,

wherein each pair of carrier devices is configured to be applied onto a respective polishing area.